



ALCOR - dRICH Readout

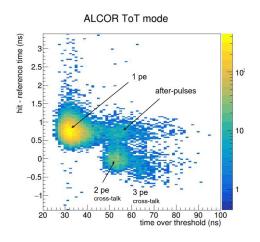
Fabio Cossio on behalf of the ALCOR group INFN Torino

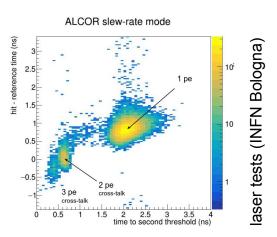
EPIC Electronics & DAQ WG meeting eRD109 Monthly Progress Reports

04.04.2024

Summary of March activities

- Validation tests of 24 ALCOR FE DUAL boards (ALCOR v2.1, for May 2024 beam test) almost completed: <u>climatic chamber</u> to study "reset glitch" effect occurring at low temperatures, yield ~ 85%
- Tested SR mode for time walk correction with <u>laser setup</u>: ToT mode cannot distinguish between afterpulses (slow-rise time, large ToT) and cross-talk (fast rise-time, large ToT), SR mode provides better separation





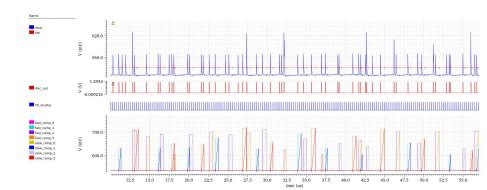




climatic chamber tests (INFN Torino)

Summary of March activities

 Design of ALCORv3 (64-channel, BGA): mixed-signal simulations with new pixel (increased bandwidth FE + digital logic with shutter)



- Design of final FEB (for ePIC) and 'fake FEB' (for dRICH 2025 activities): selection of components and connectors for PDU integration ongoing
 - <u>FEB-Carrier connector</u>: LSHM-150-01-L-RH-A-N-K-TR (FEB side) 0.5 mm, 100 places over two rows, current rating 2.0 A per pin (reduced width, easier to connect w.r.t. edge connector)
 - Mapping of <u>ALCOR bus</u> connector pins (FEB and 'fake FEB') for RDO pin-plan and routing

